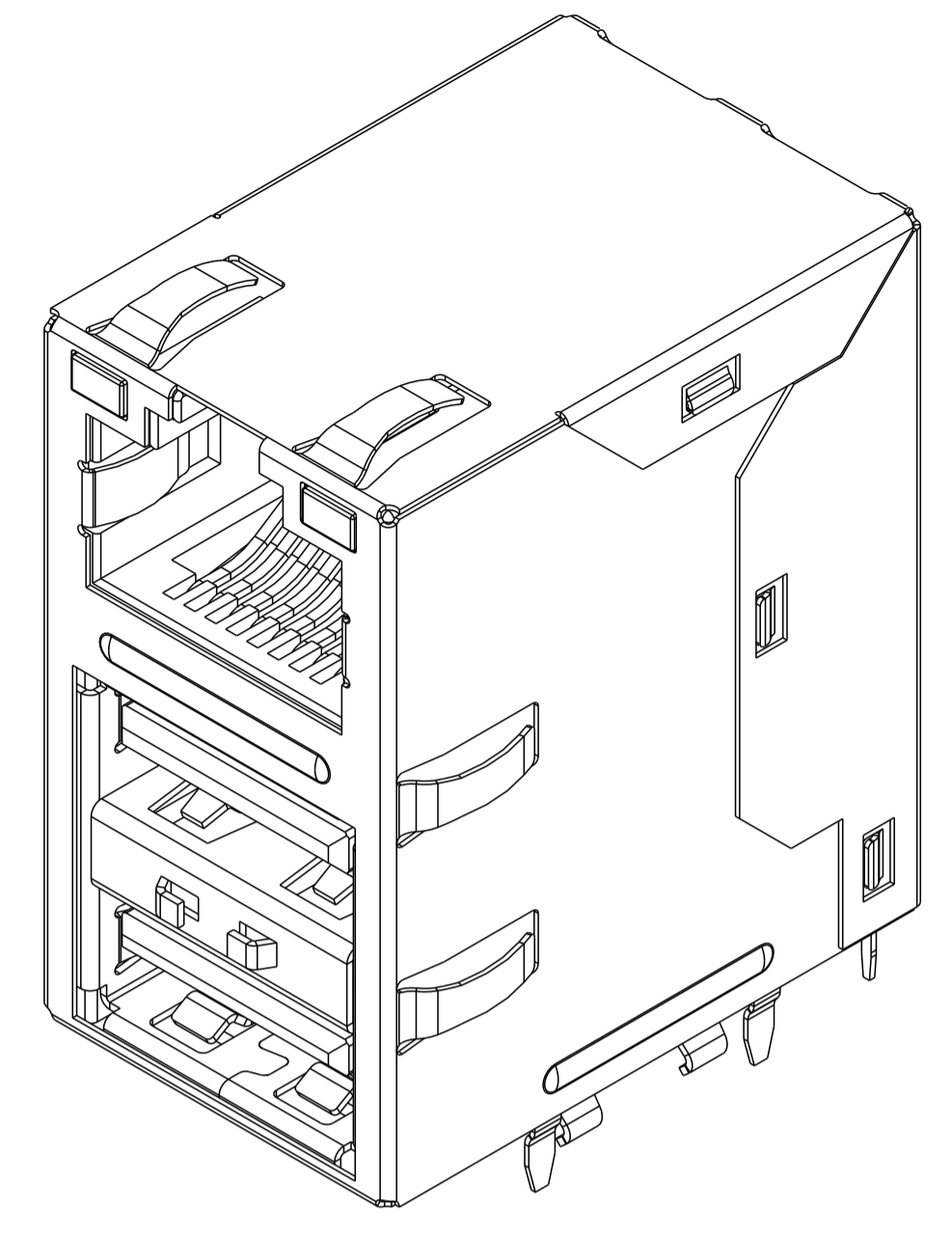
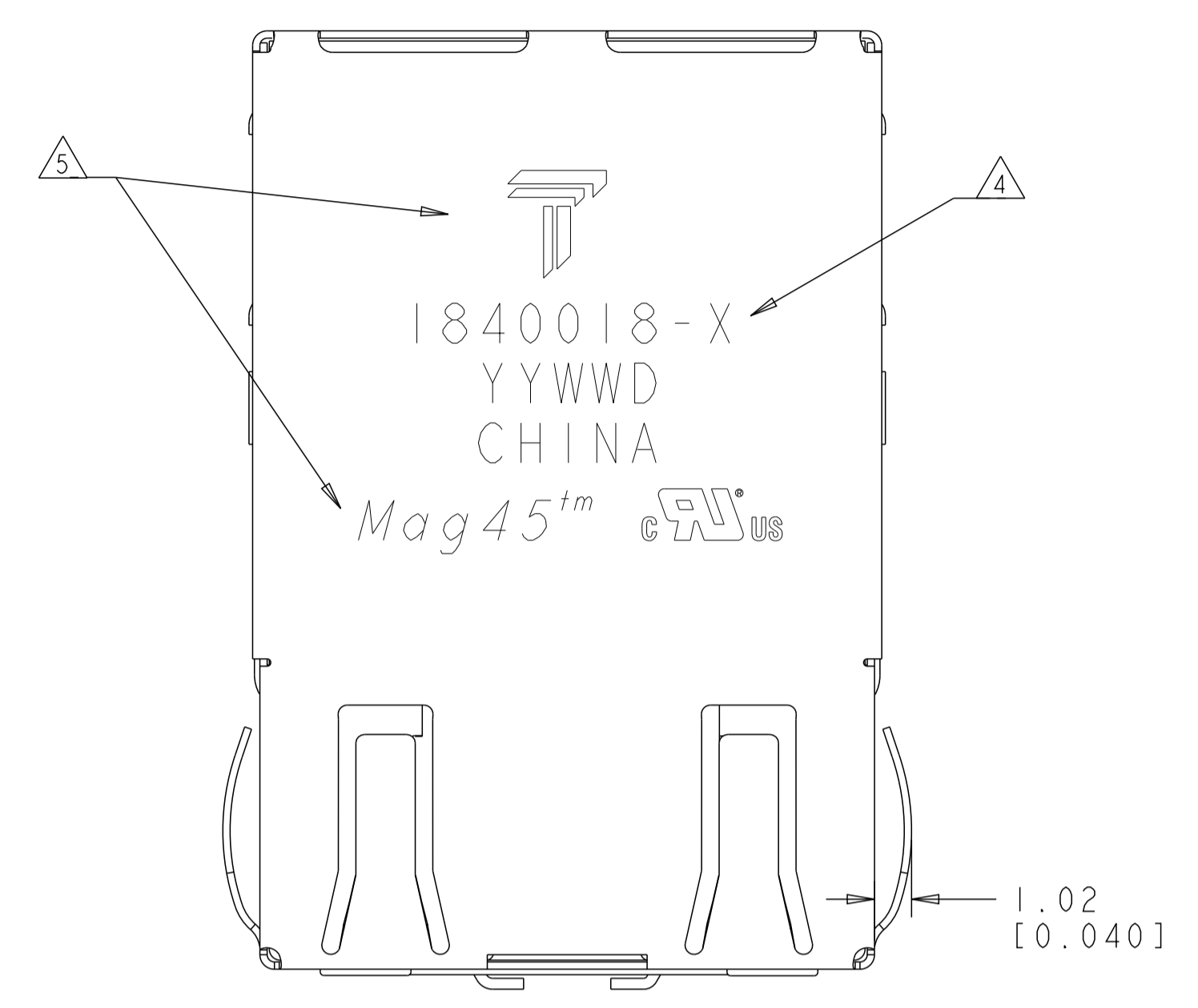


REVISIONS				
P	LTN	DESCRIPTION	DATE	APPV
F		LOGO CHANGE	07APR2013	PP KZ

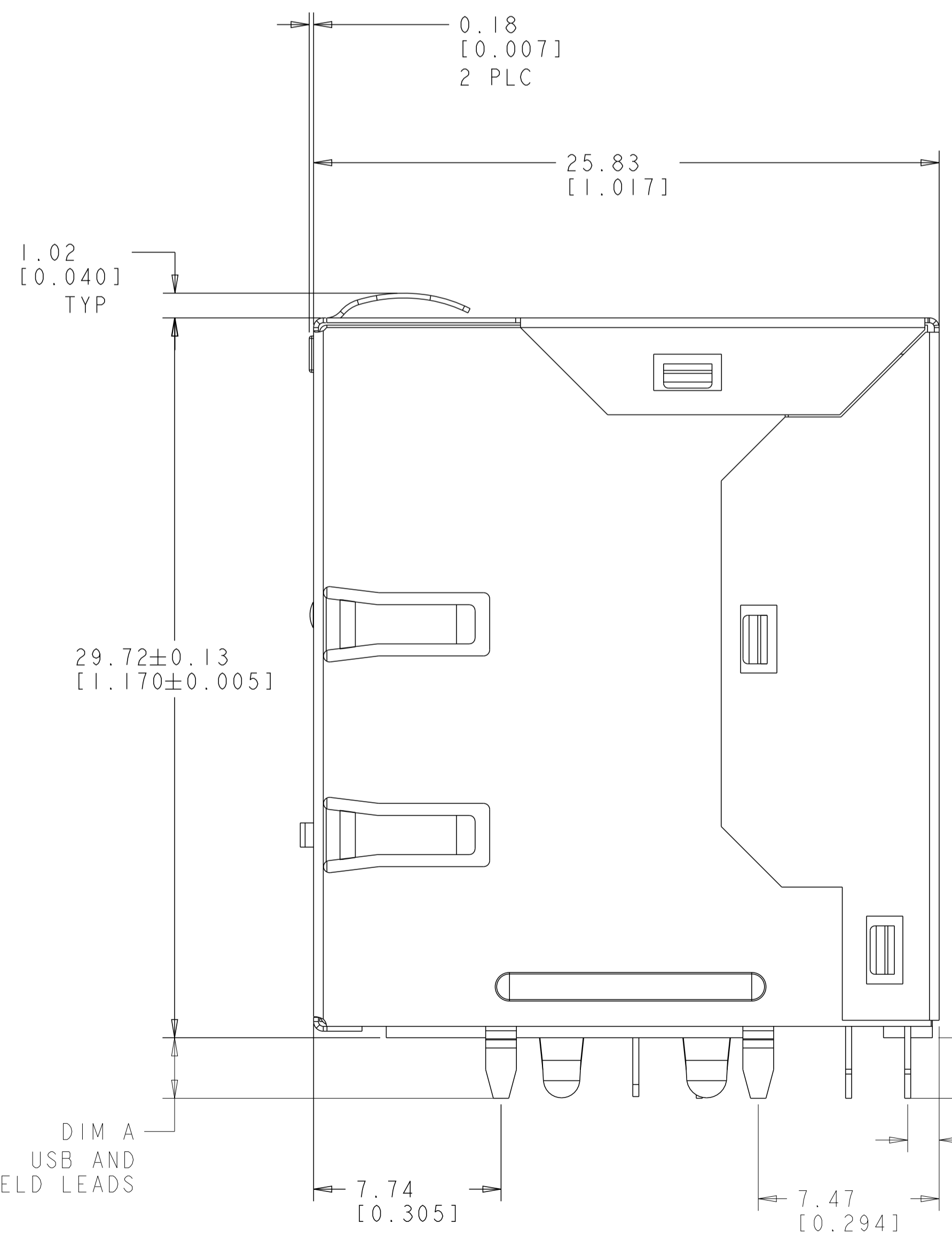
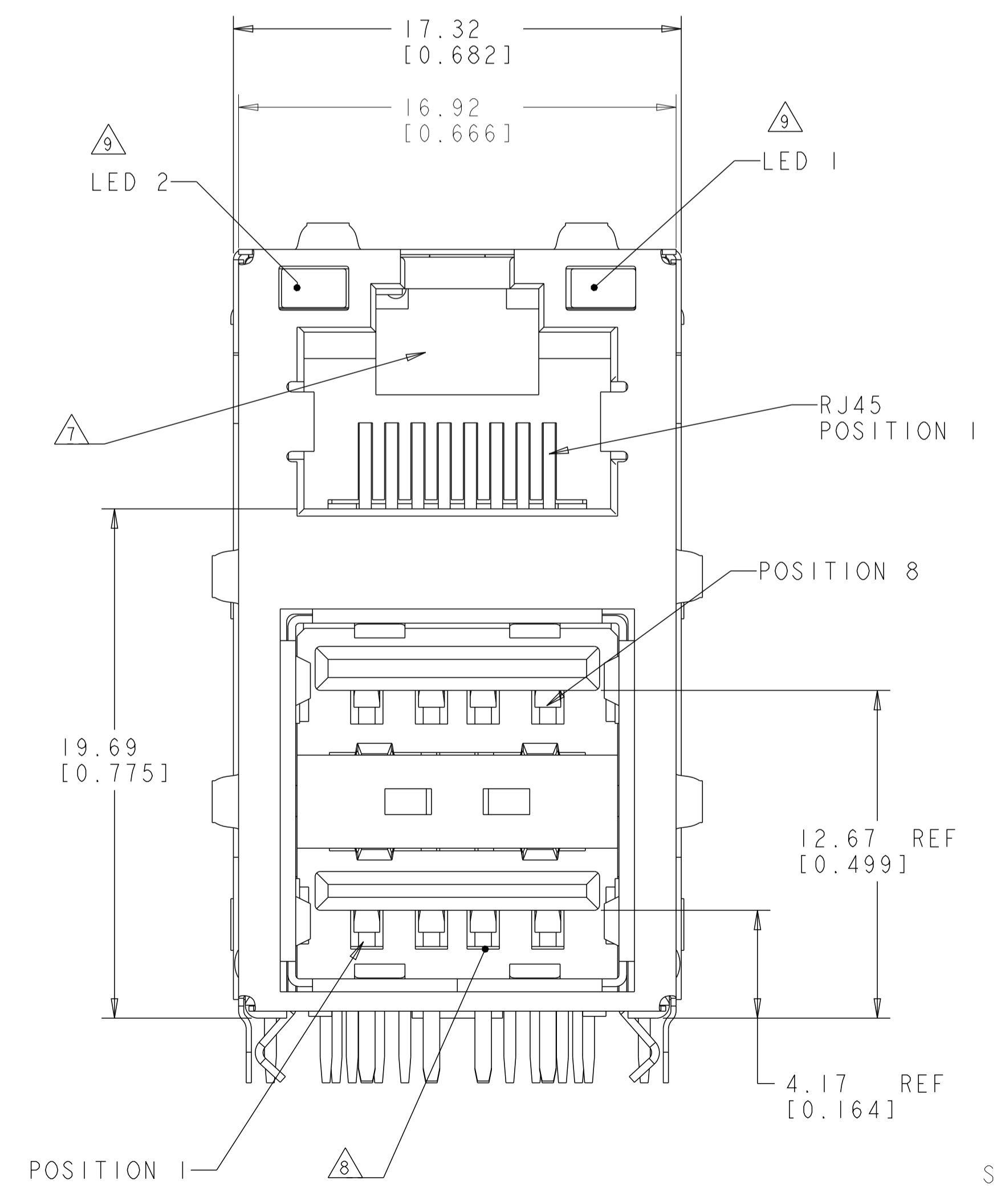


SCALE 4:1

- △ USB MATERIALS:
 SHELL: PHOSPHOR BRONZE
 HOUSING: BLACK, THERMOPLASTIC, GLASS FILLED, UL 94V-0 RATED
 CONTACT: PHOSPHOR BRONZE WITH SELECTIVE 0.76um MIN GOLD PLATING
 SPRING CLIP: PHOSPHOR BRONZE
- RJ45 MATERIALS:
 HOUSING: BLACK, THERMOPLASTIC FLAMMABILITY RATING UL 94V-0
 SHIELD: BRASS, PREPLATED WITH 0.76um SEMI-BRIGHT NICKEL,
 POST DIPPED WITH 2.54um MIN SAC SOLDER ON SOLDER TAILS.
 CONTACTS: PHOSPHOR BRONZE, 0.30mm THK, 1.27um MIN OVERALL NICKEL
 UNDERPLATE WITH SELECT 1.27um MIN GOLD AT MATING INTERFACE
 AND 2.54um MIN MATTE TIN AND/OR SAC SOLDER ON SOLDER TAILS.
- LED: DIFFUSED EPOXY LENS, 0.5 X 0.5 CARBON STEEL WIREFRAME
 LEADS PREPLATED WITH 2.03um MIN SILVER OVER 1.02um MIN NICKEL
 UNDERPLATE OVER 1.02um COPPER UNDERPLATE. POST-PLATED WITH
 2.54um MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

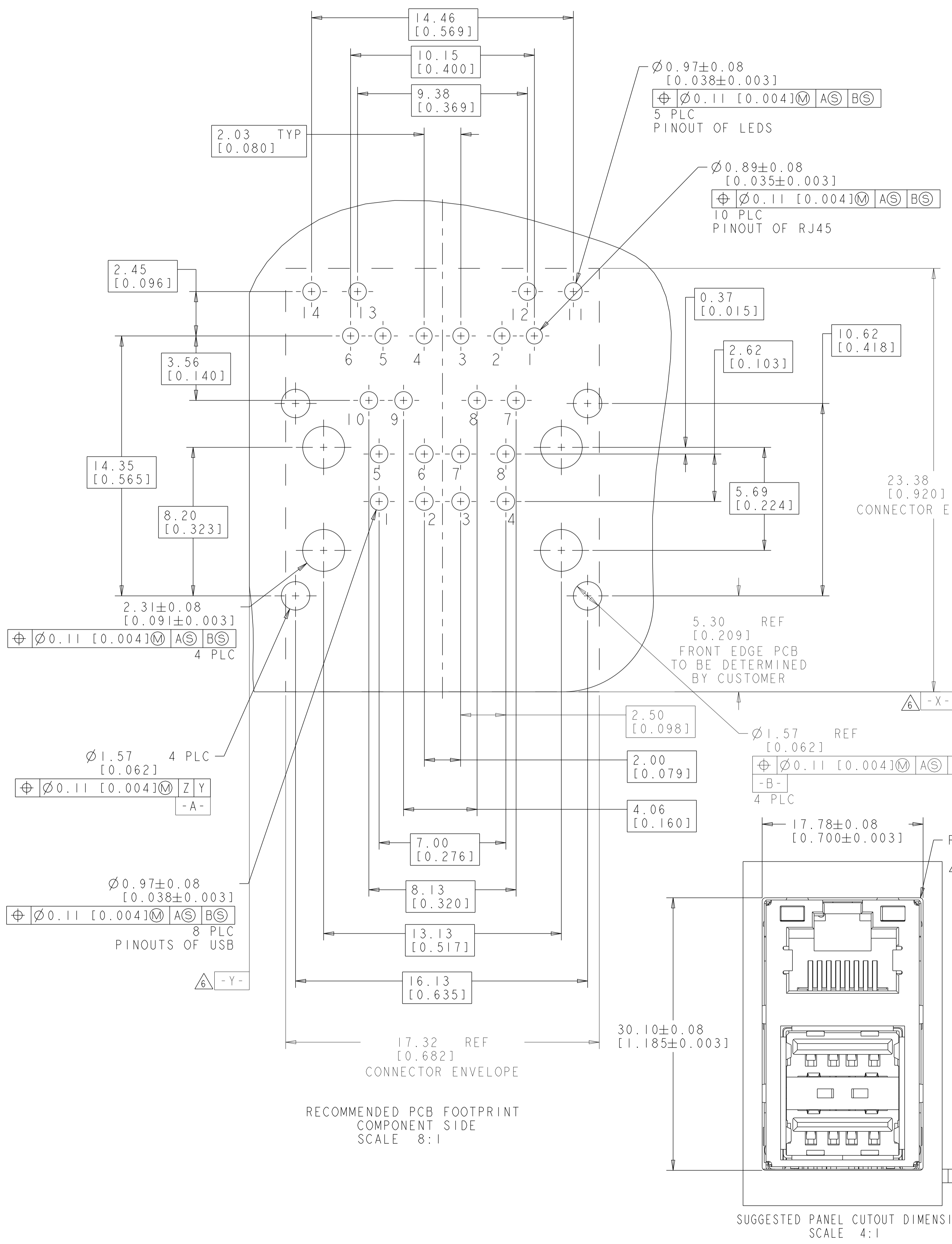
- △ MAGNETICS
 -APPLICATION : 10/100/1000 BASE-T
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO(CHIP:CABLE): 1:1 ALL FOUR PAIRS
 -OPEN CIRCUIT INDUCTANCE(OCL): 350uH MIN @100kHz, 0.1 VRMS,
 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
 -RISE TIME (10%-90%): 2.5ns TYPICAL;
 -ALL FOUR PAIRS BI-DIRECTIONAL
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1 dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 12-20LOG(f/80)dB MIN FROM 40.1 MHz TO 100MHz
 CROSSTALK ATTENUATION: 35 dB MIN FROM 0.5 MHz TO 40 MHz
 33-20LOG(f/50) dB MIN FROM 40.1 MHz TO 100 MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 40.6.1.1, ITEM b.

- 3. OPERATING TEMPERATURE: 0°C TO + 70°C.
- △ PART NUMBER, DATE CODE AND COUNTRY OF ORIGIN TO BE LOCATED IN APPROXIMATE AREA SHOWN. DATE CODE: YYWWD "YY" IS YEAR, "WW" IS WORK WEEK, "D" IS DAY OF WEEK, WITH SUNDAY=1.
- △ AGENCY APPROVAL LOGO, TRP CONNECTOR LOGO AND PRODUCT LOGO LOCATED IN APPROXIMATE AREA SHOWN.
- △ RECOMMENDED PCB THICKNESS 1.5mm (.062") THICK. DATUM LOCATION AND DIMENSION TO BE ESTABLISHED BY CUSTOMER.
- △ RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUBPART F.
- △ MATING INTERFACE COMPLIES WITH USB (UNIVERSAL SERIAL BUS) SPECIFICATION REV 2.0.
- △ LEDS WITHOUT BUILT-IN RESISTOR
 LEDS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
- 10. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

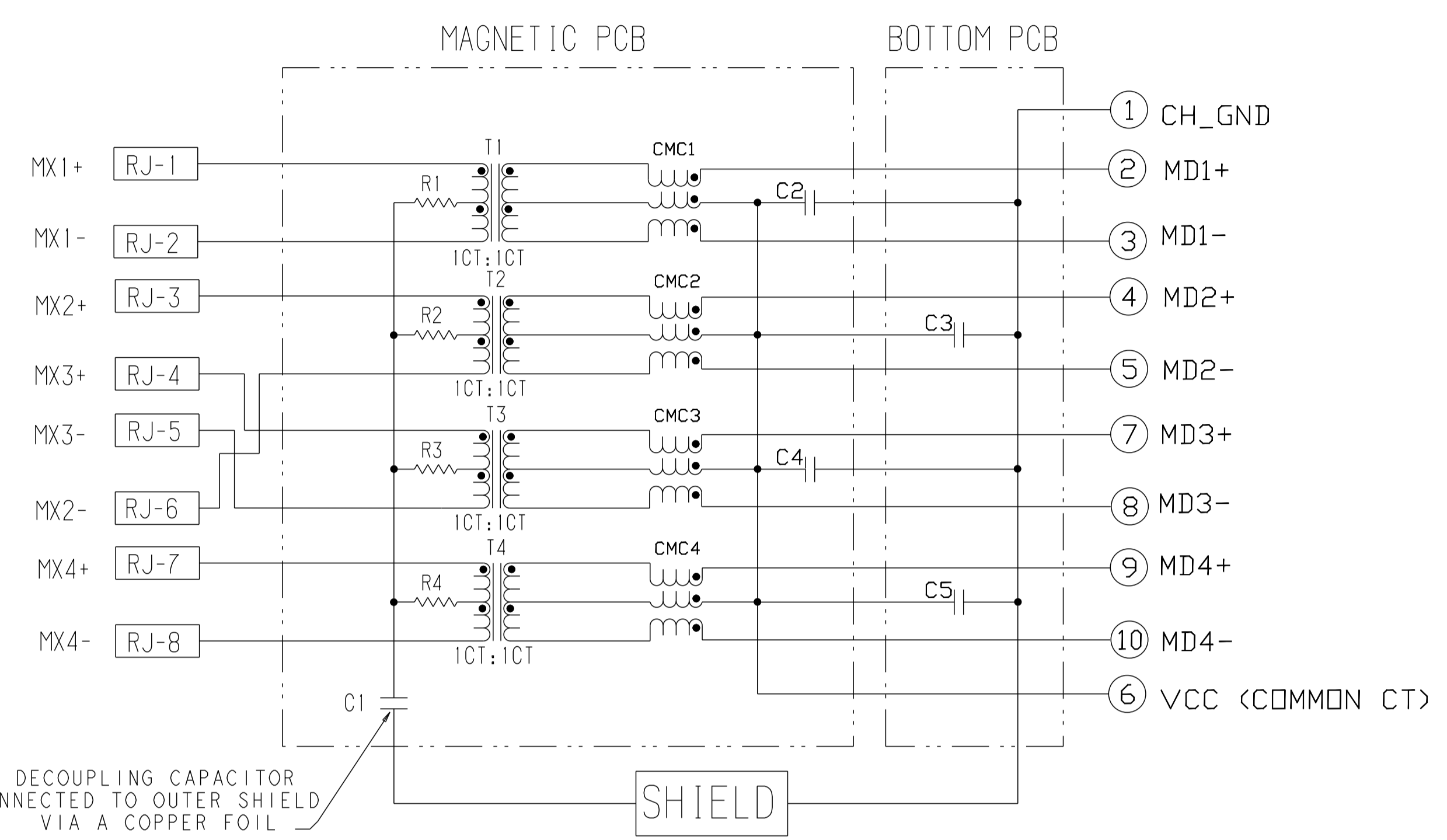


THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: YKIN LEE 29OCT2008		TRP connector Dongguan China		
DIMENSIONS: mm		CHK: QUENTIN LIU 29OCT2008		PRODUCT SPEC	NAME	RJ45 OVER DUAL USB MAG45 TM
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV: TEDDY XIANG 29OCT2008		108-104005	GIGABIT URG4TP9 CIRCUIT, W/LED	
0 PLC ±0.25	1 PLC ±0.25	2 PLC ±0.25	3 PLC ±0.25	4 PLC ±0.25	ANGLES ±0.25	
MATERIAL: △	FINISH: △	WEIGHT: -	SIZE: A1	CAGE CODE: 00779	DRAWING NO: C=1840018	
CUSTOMER DRAWING			SCALE: 6:1	SHEET: 1	OF 2	
			REV: F			

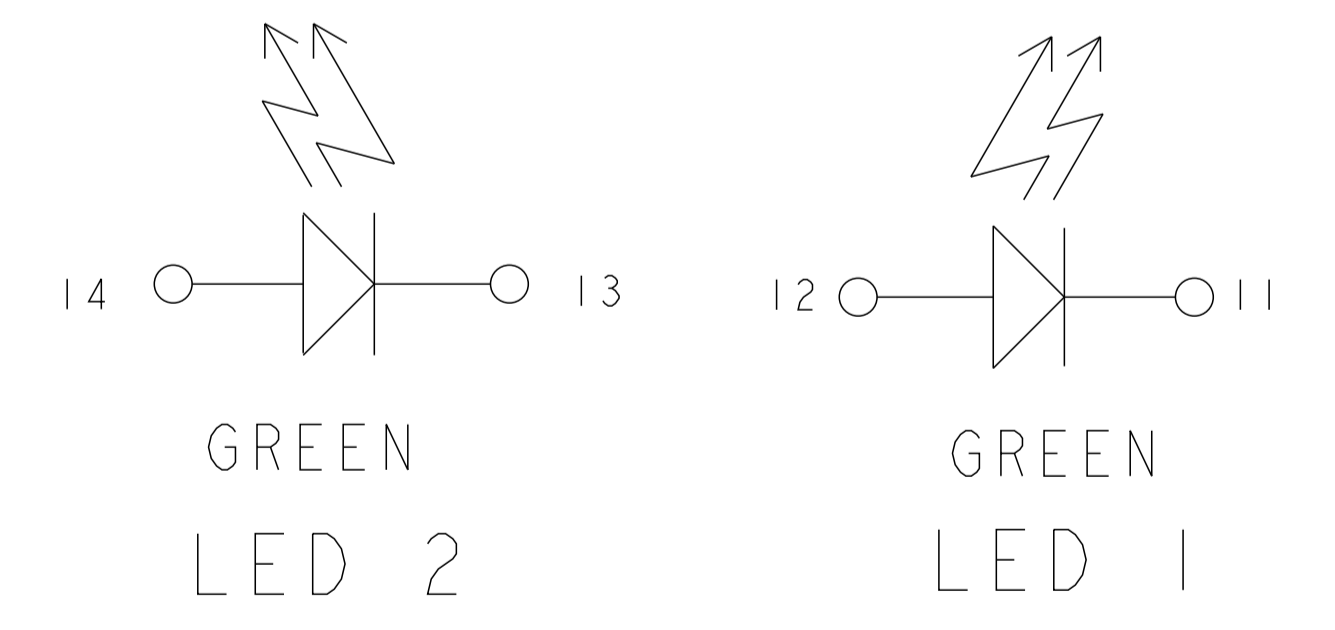
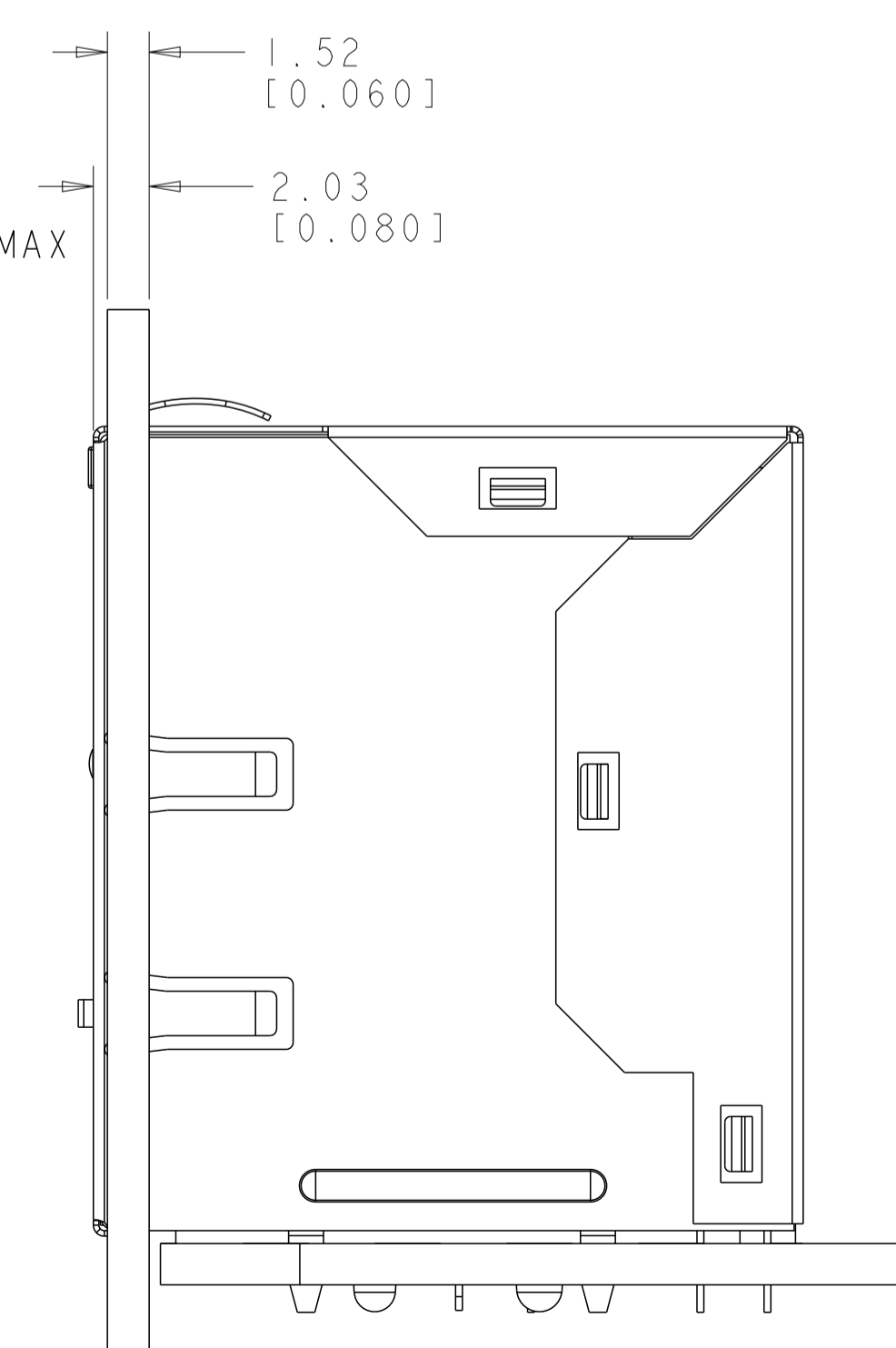
2.79 mm	2-1840018-1
2.50 mm	1840018-1
DIM A	PART NUMBER



URG47P9 GIGABIT CIRCUIT



R1~R4 = 75 Ohms, 1/16W, 5%
 C1 = 1000 pF, 2kV, 10%, X7R
 C2~C5 = 0.01uF, 50V, 10%, X7R



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: YKIN LEE 29OCT2008 CHK: QUENTIN LIU 29OCT2008 APVD: TEDDY XIONG 29OCT2008	TRP connector Dongguan China
DIMENSIONS: mm 0 PLC ±0.25 2 PLC ±0.25 3 PLC ±0.25 4 PLC ±0.25 ANGLES ±0.5	TOLERANCES UNLESS OTHERWISE SPECIFIED: 6 FINISH:	PRODUCT SPEC: 108-104005 APPLICATION SPEC:	NAME: RJ45 OVER DUAL USB MAG45 TM GIGABIT URG47P9 CIRCUIT, W/LED SIZE: A1 CAGE CODE: 100779 DRAWING NO: C=1840018 WEIGHT:
MATERIAL:		CUSTOMER DRAWING	SCALE: 6:1 SHEET: 2 OF 2 REV: F